

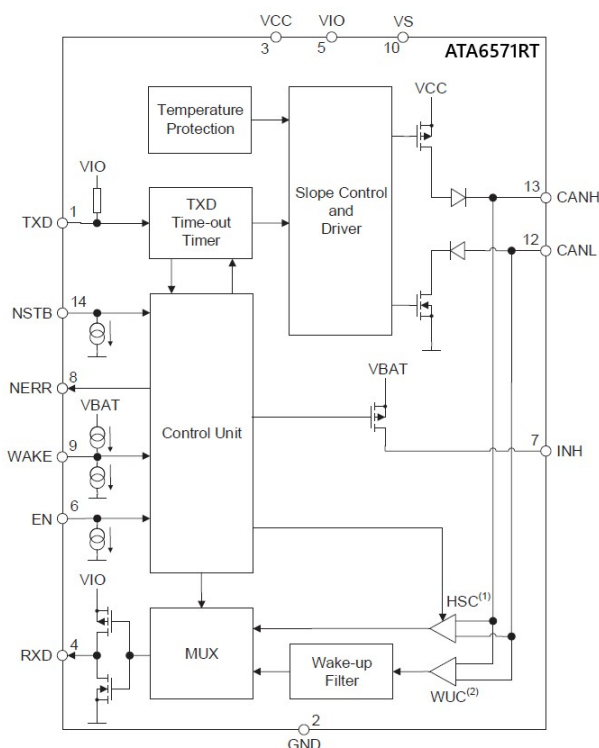
Introduction

ATA6571RT is a radiation tolerant stand-alone high-speed CAN FD transceiver that interfaces a Controller Area Network (CAN) protocol controller and the physical two-wire CAN bus. The transceiver is designed for high-speed (up to 5 Mbps) CAN FD applications in the aerospace industry, providing differential transmit and receive capability to (a microcontroller with) a CAN protocol controller. It offers improved Electromagnetic Compatibility (EMC) and ESD performance and low power consumption, as well as features such as:

- Ideal passive behavior to the CAN bus when unpowered
- Direct interfacing with 3V microcontrollers
- Advanced low-power management with local and remote wake-up support, available at all times, even when the internal VIO and VCC supplies are switched off
- Protection and diagnostic functions including bus line short-circuit and battery connection detection

The following figure shows the simplified block diagram of ATA6571RT.

Figure 1. Simplified Block Diagram



Notes:
1. High-Speed Comparator
2. Wake-Up Comparator

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1. Features

ATA6571RT has the following features:

- CAN FD Transceiver Fully Compliant to ISO 11898-2, ISO 11898-5, ISO 11898-2: 2016 and SAEJ 2962-2
- ISO 26262 Functional Safety Ready
- Wake-Up Pattern (WUP) Detection According to ISO 11898-2: 2016
- Communication Speed up to 5 Mbps
- Low Electromagnetic Emission (EME) and High Electromagnetic Immunity (EMI)
- Differential Receiver with Wide Common-Mode Range
- Functional Behavior Predictable Under All Supply Conditions
- VIO Input Allows for Direct Interfacing with 3V Microcontrollers
- Transceiver Disengages from the Bus when Not Powered-Up
- RXD Recessive Clamping Detection
- Silent Mode (Receive Only) for Node Diagnosis and Failure Containment
- High Electrostatic Discharge (ESD) Handling Capability on the Bus Pins
- Bus Pins Protected Against Transients
- Transmit Data (TXD) Dominant Time-Out Function
- Undervoltage Detection on VS, VCC and VIO Pins
- CANH/CANL Short Circuit and Overtemperature Protected
- Power-Up Diagnosis
- INH Output to the Control External Voltage Regulator
- WAKE Input Pin
- Remote Wake-Up Capability through CAN Bus
- Wake-Up Source Recognition
- Available Packages: SOIC14 and CDFP14
- Radiation Tolerance Data:
 - Total dose = 50 krad (Si)
 - Single Event Latch-up immunity > 78 MeV.cm²/mg at +125 °C
 - Detailed results about TID, SEL and SEU available upon request
 - Temperature Range: -55 °C to +125 °C

2. Space Quality Grade

For more details about Screening and qualification flows, see [Packaged Part for Aerospace and Defense Applications: Screening and Qualification Monitoring](#).

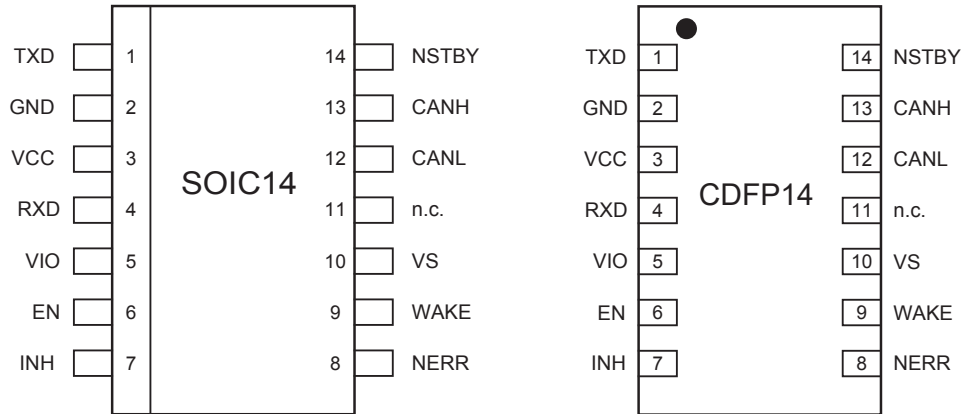
The hermetic ATA6571RT is available in several quality grades, SV is our most stringent grade, compliant with class V/ESCC9000 in terms of screening testing, qualification testing and TCI/QCI specification requirements.

The plastic ATA6571RT is also available for HiRel applications.

3. Pin Configuration

The following figure shows the pin configuration of ATA6571RT.

Figure 3-1. Pin Configuration



The following table lists the pin description of ATA6571RT.

Table 3-1. Pin Description

ATA6571RT		Symbol	Function
SOIC14	CDFP14		
1		TXD	Transmit Data Input Pin
2		GND	Ground Pin
3		VCC	Transceiver Supply Voltage Pin
4		RXD	Receive Data Output Pin
5		VIO	Supply Voltage for the I/O Pins
6		EN	Enable Control Input Pin
7		INH	Inhibit Output for Switching External Voltage Regulators
8		NERR	Error and Power-on Indication Output (Active-low)
9		WAKE	Local Wake-Up Input. Connect directly to the VS pin or the GND pin, if not used.
10		VS	Battery Supply Voltage Pin
11		NC	Not Connected
12		CANL	Low-Level CAN Bus Line
13		CANH	High-Level CAN Bus Line
14		NSTBY	Standby Mode Control Input (Active-low)

3.1. Battery Supply Voltage Pin (VS)

This is the power supply pin. An undervoltage detection circuit is implemented to avoid a malfunction or false bus messages. After switching on the VS pin, the device starts in Standby mode and the INH output is switched on.

3.2. Ground Pin (GND)

The device does not affect the CAN bus in the event of a GND disconnection.

3.3. Transceiver Supply Voltage Pin (VCC)

This is the supply pin for the CANH and CANL bus drivers, the bus differential receiver and the bus biasing voltage circuitry. The device monitors the VCC pin for undervoltage conditions.

3.4. Supply Pin for I/O Level Adapter (VIO)

This is the supply pin for the digital input/output pins. This pin must be connected to the microcontroller's supply voltage to adjust the signal levels of pins TXD, RXD, NSTBY, EN and NERR to the I/O levels of the microcontroller. The device monitors the VIO pin for undervoltage conditions.

3.5. Bus Pins (CANH and CANL)

CANH and CANL are the CAN bus terminals.

The CANL pin is a low-side driver to GND, and the CANH pin is a high-side driver to VCC. In Normal mode and if TXD is high, the CANH and CANL drivers are off, and the voltage at CANH and CANL is approximately 2.5V, provided by the internal bus biasing circuitry. This state is called recessive.

When TXD is low, CANL is pulled to GND and CANH to VCC, creating a differential voltage on the CAN bus. This state is called dominant.

In Standby mode, the CANH and CANL drivers are off. If the device is in Unpowered or Sleep mode, CANH and CANL are highly resistive with extremely low leakage current to GND, making the device ideally passive.

The CANH and CANL pins have integrated ESD protection and extremely high robustness versus external disturbance, such as EMC and electrical transients. The CANH and CANL bus outputs are short-circuit protected against GND or a positive supply voltage and are also protected against overtemperature conditions.

3.6. Transmit Data Input Pin (TXD)

This is the device input pin used to control the CAN bus level. In the application, this pin is connected to the microcontroller transmit terminal. The TXD pin has an internal pull-up toward VIO to ensure a safe defined recessive driver state in case this pin is left floating.

In Normal mode, when TXD is high or floating, the CANH and CANL drivers are off, setting the bus in the recessive state.

The TXD pin must be pulled to GND in order to activate the CANH and CANL drivers, and the bus is set to the dominant state. A TXD dominant time-out timer starts when the TXD pin is set to low. If the low state on the TXD pin persists for longer than $t_{to(dom)}$, the transmitter is disabled, releasing the bus lines to recessive state. This function prevents a hardware and/or software application failure from driving the bus lines to a permanent dominant state (blocking all network communications). The TXD dominant time-out timer is reset when the TXD pin is set to high.

The transmitter is also disabled, if the TXD pin is held low (for example, by a short circuit to GND) while the device is switched into Normal mode, the bus lines are in the recessive state. The transceiver remains in this state, until the TXD pin goes high.

3.7. Receive Data Output Pin (RXD)

In Normal and Silent mode, this pin reports the state of the CAN bus to the microcontroller. In the application, this pin is connected to the microcontroller receive terminal. RXD is high when the bus is recessive. When the bus is dominant, RXD is low.

The output is a push-pull structure; the high side is connected to VIO and the low side to GND.

In Standby mode, the RXD is switched to VIO. When a wake-up event is detected, the RXD will be forced to low.

A RXD recessive clamping function (see [RXD Recessive Clamping](#) section) is implemented. This fail-safe feature prevents the controller from sending data on the bus if the RXD line is clamped to high (for example, recessive).

3.8. Inhibit Output Pin (INH)

The inhibit output pin provides an internal switch toward the VS pin and is used to control external voltage regulators. If the device is in Normal or Standby mode, the inhibit high-side switch is turned

on. When the device is in Sleep mode, the inhibit switch is turned off, thus disabling the connected external voltage regulators or other connected external devices.

A wake-up event on the CAN bus or at the WAKE pin switches the INH pin to the VS level. After a system power-up (VS rises from zero), the INH pin switches to the VS level automatically.

3.9. Wake Pin (WAKE)

This input pin wakes up the device from Sleep mode. It is usually connected to an external switch in the application to generate a local wake-up. If the WAKE pin is not needed in the application, it must be connected to VS or GND to ensure optimal EMI performance.

The WAKE pin has a special design structure and is triggered by a low-to-high or a high-to-low transition, allowing maximum flexibility when designing a local wake-up circuit.

An internal filter is implemented to avoid a false wake-up event due to parasitic pulses. A serial resistor must be inserted to limit the input current mainly during transient pulses and ESD. The recommended resistor value is 10 kΩ. An external 10 nF capacitor is recommended for better EMC and ESD performances.

To reduce the battery current during Low-Power mode, the internal pull-up/pull-down circuit follows the logic level at the WAKE pin:

- A high level on the pin is followed by an internal pull-up toward VS
- A low level is followed by an internal pull-down towards GND

3.10. Enable Pin (EN)

The enable input pin together with the NSTBY pin controls the operating mode of the device.

The internal pull-down on the EN pin forces the transceiver into Recessive mode if EN is disconnected.

3.11. Error Indication Pin (NERR)

The NERR pin signals the status of the device. ATA6571RT supports system diagnosis using seven internal flags. Five of these flags can be polled by the controller through NERR pin. The signaled flag on the pin NERR depends on the active operating mode and on a number of other conditions. Switching between modes gives access to the different diagnostic flags through the NERR pin.

3.12. Standby Mode Control Pin (NSTBY)

The NSTBY input pin together with the EN pin controls the operating mode of the device. The NSTBY pin provides a pull-down current to force the transceiver into Standby mode if STBY is disconnected.

4. Functional Description

The ATA6571RT high-speed CAN transceiver offers a number of operating modes, diagnostic features and fail-safe features that enable enhanced system reliability and advanced power management.

4.1. Device Operation Modes

The control pins (NSTBY and EN) are used to select one of the five operating modes supported by ATA6571RT. Switching between modes allows access to a number of diagnostic flags through the NERR pin. The following table lists how to switch between modes and [Figure 4-1](#) illustrates the different mode transitions.

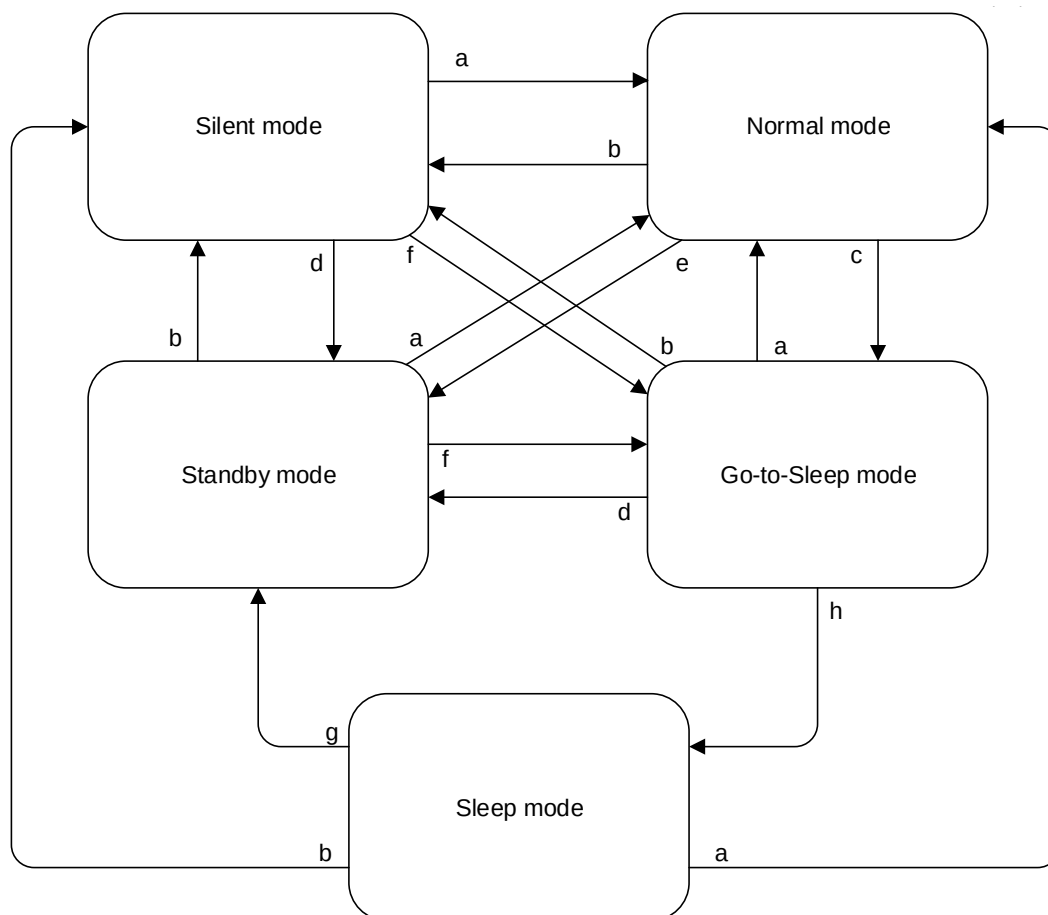
Table 4-1. Operating Modes

Mode	Diagnostic Flags			NSTBY ³	EN	INH
	UV _{VCC/IO} ¹	UV _{VS}	Wake ²			
From Normal, Silent, Standby and Go-to-Sleep modes						
Sleep mode	Set	—	—	—	—	Floating
Standby mode	Cleared	Set	—	High	—	High
Standby mode	Cleared	—	Set	Low	—	High
Standby mode	Cleared	—	Cleared	Low	Low	High
Go-to-Sleep mode	Cleared	—	Cleared	Low	High	High
Silent mode	Cleared	Cleared	—	High	Low	High
Normal mode	Cleared	Cleared	—	High	High	High
From Sleep mode						
Sleep mode	Set	—	—	—	—	Floating
Standby mode	Cleared	Set	—	High	—	High
Standby mode	Cleared	—	Set	Low	—	High
Sleep mode	Cleared	—	Cleared	Low	—	Floating
Silent mode	Cleared	Cleared	—	High	Low	High
Normal mode	Cleared	Cleared	—	High	High	High

Notes:

1. Setting the UV_{VCC/IO} flag clears the Wake flag.
2. Setting the Wake flag clears the UV_{VCC/IO} flag.
3. A low-to-high transition on pin NSTBY clears the UV_{VCC/IO} flag.

Figure 4-1. Operating Modes



Where:

- a = NSTBY = 1, EN = 1
- b = NSTBY = 1, EN = 0
- c = NSTBY = 0, EN = 1
- d = NSTBY = 0, EN = 0 (wake flag set)
- e = NSTBY = 0, EN = 0
- f = NSTBY = 0, EN = 1 (wake flag cleared)
- g = NSTBY = 0 (wake flag set)
- h = wake flag cleared, $t > t_{\text{hold(min)}}$

4.1.1. Normal Mode

In Normal mode, the transceiver can transmit and receive data through the bus lines CANH and CANL. The output driver stage is active and drives data from the TXD input to the CAN bus. The High-Speed Comparator (HSC) converts the analog data on the bus lines into digital data, which is output to the RXD pin. The bus biasing is set to $V_{CC}/2$ and the undervoltage monitoring of VCC is active. The slope of the output signals on the bus lines is controlled and optimized in a way that guarantees the lowest possible Electromagnetic Emission (EME). The INH pin is active, so voltage regulators controlled by the INH pin are active too.

4.1.2. Silent Mode

This Receive-Only mode can be used to test the connection of the bus medium. In Silent mode, ATA6571RT can still receive data from the bus, but the transmitter is disabled and therefore no

data can be sent to the CAN bus. The bus pins are released to recessive state ($V_{VCC/2}$). All other IC functions, including the HSC, continue to operate as they do in Normal mode. The Silent mode can be used to prevent a faulty CAN controller from disrupting network communication.

4.1.3. Standby Mode

The Standby mode is the first level of power-saving mode for ATA6571RT, offering reduced current consumption. In this mode, the transceiver is not able to transmit or correctly receive data through the bus lines. The transmitter and the HSC are switched off to reduce current consumption and only the low-power Wake-Up Comparator (WUC) monitors the bus lines for a valid wake-up signal. The bus pins are biased at ground level.

Pin INH is still active, so voltage regulators controlled by this pin are also active.

Pins RXD and NERR reflect any active wake-up requests (provided that VIO and VS are present).

4.1.4. Go-to-Sleep Mode

The Go-to-Sleep mode is the controlled route for entering Sleep mode. In Go-to-Sleep mode, the transceiver behaves as in Standby mode, with the addition that a Go-to-Sleep command is issued to the transceiver. The transceiver remains in Go-to-Sleep mode for the minimum hold time (t_{hold}) before entering Sleep mode. The transceiver does not enter Sleep mode if the state of pin NSTBY or pin EN is changed or if the Wake flag is set before t_{hold} has elapsed.

4.1.5. Sleep Mode

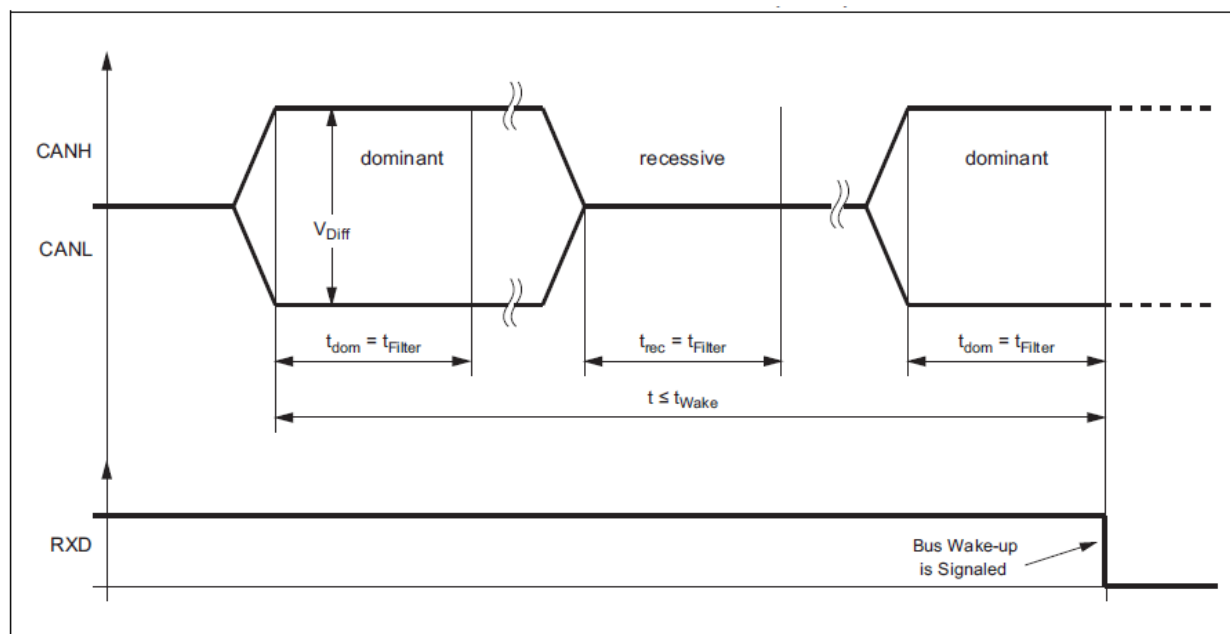
The Sleep mode is the highest power-saving mode of the device. In this mode, the INH output is switched off. Therefore the external voltage regulator(s) controlled by this pin is also switched off. This is the only difference between Sleep mode and Standby mode.

The Sleep mode is entered through Go-to-Sleep mode, and also when the undervoltage detection time on either VCC or VIO elapses before the relevant voltage level has recovered. Pins NSTBY, EN, and the Wake flag can be used to wake up a node from Sleep mode.

4.1.6. Remote Wake-Up through the CAN Bus

In Standby and Sleep mode, the bus lines are biased to ground to reduce current consumption to a minimum. ATA6571RT monitors the bus lines for a valid WUP as specified in the ISO 11898-2: 2016. This filtering helps to avoid spurious wake-up events, which can be triggered by scenarios such as a dominant clamped bus or by a dominant phase due to noise, spikes on the bus, transients or EMI.

The wake-up pattern consists of at least two consecutive dominant bus levels for a duration of at least t_{Filter} , each separated by a recessive bus level with a duration of at least t_{Filter} . Dominant or recessive bus levels shorter than t_{Filter} are always ignored. The complete dominant-recessive-dominant pattern must be received within the bus wake-up time-out time t_{wake} , to be recognized as a valid wake-up pattern, as shown in the following figure. Otherwise, the internal wake-up logic is reset and then the complete wake-up pattern must be retransmitted to trigger a wake-up event. Pin RXD remains at high level until a valid wake-up event is detected. During Normal mode, at a VCC or VIO undervoltage condition or when the complete wake-up pattern is not received within t_{wake} , no wake-up is signaled at the RXD pin.

Figure 4-2. Timing of the Bus WUP in Standby Mode

When a valid CAN WUP is detected on the bus, the RXD pin switches to low to signal a wake-up request.

4.2. Internal Flags

For Fail-Safe Fallback mode control and system diagnosis, ATA6571RT has seven internal flags. Controller polls five of these flags through NERR pin. Depending on the current operating mode and on a number of other conditions, a different flag is available on the NERR pin. The following table lists the access and control of these flags.

Table 4-2. Internal Flags Accessed through Pin NERR

Internal flag	Available flag on pin NERR ¹	Flag is cleared
UV _{VCC/VIO}	No	By setting the Pwon or Wake flags, by a low-to-high transition on NSTBY or when both VIO and VCC have recovered.
UV _{VS}	No	When VS has recovered.
Pwon	In Silent mode (coming from Standby mode, Go-to-Sleep mode, or Sleep mode).	When entering Normal mode.
Wake	In Standby mode, Go-to-Sleep, and Sleep mode (provided that VIO and VS are present).	When entering Normal mode or by setting the UV _{VCC/VIO} flag.
Wake-up source	In Normal mode (before the fourth dominant-to-recessive edge on pin TXD ²).	When leaving Normal mode.
Bus failure	In Normal mode (after the fourth dominant-to-recessive edge on pin TXD ²).	When re-entering Normal mode or by setting the Pwon flag.
Local failure	In Silent mode (coming from Normal mode).	When entering Normal mode or when RXD is dominant while TXD is recessive (provided that all local failures are resolved) or by setting the Pwon flag.

Notes:

1. Pin NERR is an active-low output, so a low level indicates a set flag and a high level indicates a cleared flag. Allow pin NERR to stabilize for at least 8 μ s after changing operating modes.
2. Allow a TXD dominant time of at least 4 μ s per dominant-recessive cycle.

4.2.1. UV_{VCC/VIO} Flag

UV_{VCC/VIO} is the VCC and/or VIO undervoltage detection flag. The flag is set when the voltage on pin VCC drops below the VCC undervoltage detection voltage, V_{VCC_UV} , for longer than the undervoltage detection time, $t_{VSUP_UV_set}$, or when the voltage on pin VIO drops below V_{VIO_UV} for longer than $t_{VSUP_UV_set}$. When the UV_{VCC/VIO} flag is set, the transceiver enters Sleep mode to save power and to ensure the bus is not disturbed. In Sleep mode the voltage regulators connected to pin INH are disabled, avoiding any extra power consumption that might be caused by a short-circuit condition.

Any wake-up request, setting the Pwon flag or a low-to-high transition on NSTBY clears UV_{VCC/VIO} and the timers, allowing the voltage regulators to reactivate (at least until UV_{VCC/VIO} is set again). UV_{VCC/VIO} is also cleared if both VCC and VIO recover for longer than the undervoltage recovery time, $t_{VSUP_UV_clear}$. The transceiver then switches to the operating mode indicated by the logic levels on pins NSTBY and EN (see [Device Operation Modes](#) section).

4.2.2. UV_{VS} Flag

The UV_{VS} is the VS undervoltage detection flag. This flag is set when the voltage on pin VS drops below $V_{VS_UV_CAN_Set}$. When UV_{VS} is set, the transceiver enters Standby mode to save power and disengages from the bus (zero load). UV_{VS} is cleared when the voltage on pin VS recovers. The transceiver then switches to the operating mode indicated by the logic levels on pins NSTBY and EN (see [Device Operation Modes](#) section).

4.2.3. Pwon Flag

The Pwon is the VS power-on flag. This flag is set when the voltage on pin VS recovers after previously dropping below V_{VS_PWROFF} (usually because the battery was disconnected). Setting the Pwon flag clears the UV_{VCC/VIO} flag and timers. The Wake and Wake-Up Source flags are set to ensure consistent system power-up under all supply conditions. In Silent mode, the Pwon flag can be polled through pin NERR (see [Table 4-2](#)). The flag is cleared when the transceiver enters Normal mode.

4.2.4. Wake Flag

The Wake flag is set when the transceiver detects a local or remote wake-up request. A local wake-up request is detected when the logic level on pin WAKE changes and the new level remains stable for at least t_{wake} . A remote wake-up request is triggered by two bus dominant states of at least $t_{wake(busdom)}$ with the first dominant state followed by a recessive state of at least $t_{wake(busrec)}$ (provided the dominant-recessive-dominant pattern is completed within $t_{to(wake)bus}$). The Wake flag can be set in Standby mode, Go-to-Sleep mode or Sleep mode. Setting the Wake flag clears the UV_{VCC/VIO} flag and timers. Once set, the Wake flag status is immediately available on pins NERR and RXD (if VIO and VS are present). This flag is also set at power-on and cleared when the UV_{VCC/VIO} flag is set or the transceiver enters Normal mode.

4.2.5. Wake-Up Source Flag

The wake-up source recognition is provided through the Wake-Up Source flag, which is set when the Wake flag is set by a local wake-up request through the WAKE pin. The Wake-Up Source flag can be polled through the NERR pin in Normal mode (see [Table 4-2](#)). This flag is also set at power-on and cleared when the transceiver leaves the Normal mode.

4.2.6. Bus Failure Flag

The Bus Failure flag is set if the transceiver detects a bus line short-circuit condition to VS, VCC or GND during four consecutive dominant-recessive cycles on pin TXD, while trying to drive the dominant bus lines. The Bus Failure flag can be polled through the NERR pin in Normal mode (see [Table 4-2](#)). This flag is cleared at power-on or when the transceiver re-enters Normal mode.

4.2.7. Local Failure Flag

In Normal and Silent modes, the transceiver can detect five different local failure events, any of which causes the Local Failure flag to set. The five local failure events are: TXD dominant clamping,

TXD-to-RXD short circuit, bus dominant clamping, an overtemperature event, and an RXD recessive clamping event (see [Fail-Safe Features](#) section). The Local Failure flag can be polled through the NERR pin in Silent mode (see [Table 4-2](#)). This flag is cleared at power-on, when entering Normal mode or when RXD is dominant while TXD is recessive, provided that all local failures have been resolved.

4.3. Fail-Safe Features

The ATA6571RT can detect a number of different local failure conditions. Any of these failures sets the Local Failure flag and in most cases the transmitter of the transceiver is disabled.

4.3.1. TXD Dominant Time-Out Function

A permanent low level on pin TXD (due to a hardware or software application failure) would drive the CAN bus into a permanent dominant state, blocking all network communication. The TXD dominant time-out function prevents such a network lock-up by disabling the transmitter. The TXD dominant time-out timer is started when the TXD pin is set to low. If the low state on the TXD pin persists for longer than $t_{to(dom)}$, the transmitter is disabled, releasing the bus lines to a recessive state. The $t_{to(dom)}$ dominant time-out timer defines a minimum possible bit rate of 40 kbps. The transmitter remains disabled until the Local Failure flag is cleared.

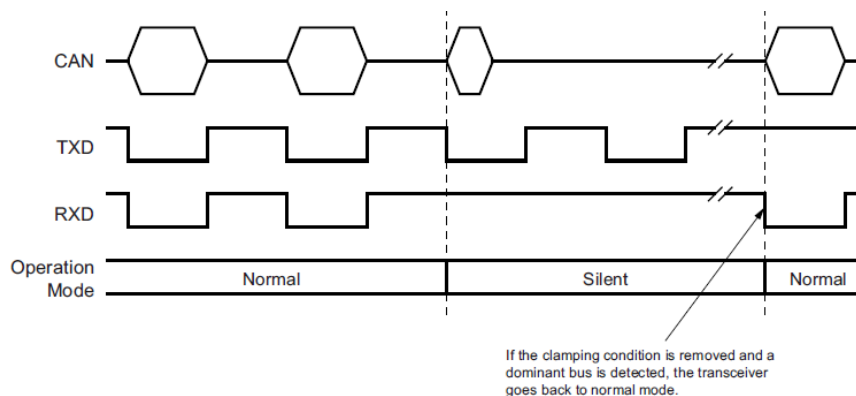
4.3.2. TXD-to-RXD Short-Circuit Detection

A short circuit between pins RXD and TXD would lock the bus in a permanent dominant state once it has been driven dominant, because the low-side driver of RXD is typically stronger than the high-side driver of the controller connected to TXD. The TXD-to-RXD short-circuit detection prevents this network lock-up by disabling the transmitter. The transmitter remains disabled until the Local Failure flag is cleared.

4.3.3. RXD Recessive Clamping

This fail-safe feature prevents the controller from sending data to the bus if its RXD line is clamped to high (for example, recessive). That is, if the RXD pin cannot signal a dominant bus state because it is shorted to VCC, the transmitter within the ATA6571RT is disabled to avoid possible data collisions on the bus. In Normal and Silent mode, the device permanently compares the state of the the HSC with the state of the RXD pin. If the HSC indicates a dominant bus state for more than $t_{RXD_rec_clmp}$, without the RXD pin indicating the same, a recessive clamping situation is detected. The RXD recessive clamping detection is reset (LOCFAIL flag removed) by either entering Normal or unpowered mode or if the RXD pin is showing a dominant (for example, LOW) level again.

Figure 4-3. RXD Recessive Clamping Detection



4.3.4. Bus Dominant Clamping Detection

A CAN bus short circuit (to VS, VCC or GND) or a failure in one of the other network nodes can result in a differential voltage on the bus, high enough to represent a bus dominant state. Because

a node does not start transmission if the bus is dominant, the normal bus failure detection does not detect this failure, but the bus dominant clamping detection will. The Local Failure flag is set if the dominant state on the bus persists for longer than $t_{\text{BUS_dom}}$. By checking this flag, the controller can determine if a clamped bus is blocking network communication. There is no need to disable the transmitter. RXD is low as long as the bus is still dominant and goes high when the bus is released to high.

Note: The Local Failure flag does not retain a bus dominant clamping failure and is released as soon as the bus returns to the recessive state.

4.3.5. Overtemperature Detection

The transceiver is protected against overtemperature conditions. If the junction temperature exceeds the shutdown junction temperature, T_{Jsd} , the transmitter is disabled until the Local Failure flag is cleared.

4.3.6. Bus Wake-Up only at Dedicated Wake-Up Pattern

Due to the implementation of the wake-up filtering, the ATA6571RT does not wake up when the bus is in a long dominant phase, it only wakes up due to the wake-up pattern specified in the ISO 11898-2: 2016. This means that for a valid wake-up at least two consecutive dominant bus levels for a duration of at least t_{Filter} , each separated by a recessive bus level with a duration of at least t_{Filter} must be received from the bus. Dominant or recessive bus levels shorter than t_{Filter} are always ignored. The complete dominant-recessive-dominant pattern (as shown in [Figure 4-2](#)) must be received within the bus wake-up time-out time t_{wake} to be recognized as a valid wake-up pattern. This filtering leads to a higher robustness against EMI and transients and reduces therefore the risk of an unwanted bus wake-up significantly.

4.3.7. Undervoltage Detection on Pins VS, VCC and VIO

If V_{VS} , V_{VCC} or V_{VIO} drop below their respective undervoltage detection levels ($V_{\text{VS_UV_CAN_Set}}$, $V_{\text{VCC_UV}}$ and $V_{\text{VIO_UV}}$ (see [Electrical Characteristics](#) section), the transceiver switches off and disengages from the bus until V_{VS} , V_{VCC} and V_{VIO} recover. The low-power wake-up comparator and local wake-up are switched off during a VS undervoltage.

5. Absolute Maximum Ratings

Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 5-1. Absolute Maximum Ratings

Parameters	Symbol	Minimum	Maximum	Unit
CANH, CANL DC Voltage	V_{CANH}, V_{CANL}	-27	+42	V
Transient Voltage, according to ISO 7637 part 2		-150	+100	V
Maximum Differential Bus Voltage	V_{Diff}	-25	+25	V
DC Voltage on Pins TXD, RXD, NSTBY, EN, NERR, VIO	V_x	-0.3	+3.6	V
DC Voltage on Pins VS, WAKE, INH, VCC	$V_{VS}, V_{WAKE}, V_{INH}, V_{VCC}$	-0.3	+5.5	V
Storage Temperature	T_{stg}	-55	+150	°C
Virtual Junction Temperature	T_{vj}	-55	+175	°C

6. Thermal Characteristics

The following tables list the thermal characteristics.

Table 6-1. Thermal Characteristics SOIC14

Parameters	Symbol	Minimum	Typical	Maximum	Unit
Junction-to-ambient Thermal Resistance	R_{JA}	—	75.3	—	K/W
Junction-to-case Thermal Resistance (Air environment)	R_{JC_AIR}	—	29.9	—	K/W
Junction-to-case Thermal Resistance (Vacuum environment)	R_{JC_VAC}	—	1.8	—	K/W
Thermal Shutdown of the Bus Drivers	T_{Jsd}	170	—	200	°C
Thermal Shutdown Hysteresis	T_{Jsd_hys}	—	15	—	°C

Table 6-2. Thermal Characteristics CDFP14

Parameters	Symbol	Minimum	Typical	Maximum	Unit
Junction-to-ambient Thermal Resistance	R_{JA}	—	136.4	—	K/W
Junction-to-case Thermal Resistance (Air environment)	R_{JC_AIR}	—	37.6	—	K/W
Junction-to-case Thermal Resistance (Vacuum environment)	R_{JC_VAC}	—	34.7	—	K/W
Thermal Shutdown of the Bus Drivers	T_{Jsd}	170	—	200	°C
Thermal Shutdown Hysteresis	T_{Jsd_hys}	—	15	—	°C

7. Electrical Characteristics

All parameters valid for $T_{amb} = -55\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$; $T_{vj} \leq 170\text{ }^{\circ}\text{C}$; $4.5\text{V} \leq V_{VS} \leq 5.5\text{V}$; $4.5\text{V} \leq V_{VCC} \leq 5.5\text{V}$; $2.8\text{V} \leq V_{VIO} \leq 3.6\text{V}$; all voltages are defined with respect to ground; $R_{(CANH-CANL)} = 60\Omega$; $C_L = 100\text{ pF}$; typical values are given at $V_{VS} = 5\text{V}$, $T_{amb} = +25\text{ }^{\circ}\text{C}$; unless otherwise noted.

The following table lists the electrical characteristics.

Table 7-1. Electrical Characteristics

No.	Parameters	Test Conditions	Pin	Sym.	Min.	Typ.	Max.	Unit	Type*
VS									
0.10	Supply Voltage Threshold for Power-On Detection	V _{VS} rising	VS	V _{VS_PWRON}	—	—	4.8	V	B
0.20	Supply Voltage Threshold for Power-off Detection	V _{VS} falling	VS	V _{VS_PWROFF}	2.8	—	3.1	V	A
0.30	Supply Voltage Threshold for CAN TRX Undervoltage Detection Release	V _{VS} rising	VS	V _{VS_UV_CAN_Clear}	4.3	—	4.6	V	A
0.40	Supply Voltage Threshold for CAN TRX Undervoltage Detection	V _{VS} falling	VS	V _{VS_UV_CAN_Set}	4.2	—	4.5	V	A
0.50	VS Supply Current	Standby mode; V _{INH} = V _{WAKE} = V _{VS}	VS	I _{VS_Stby}	—	—	32	μA	A
0.51		Normal or Silent mode	VS	I _{VS_Norm}	—	—	350	μA	A
0.52		Sleep mode; V _{INH} = V _{VCC} = V _{VIO} = 0V; V _{WAKE} = V _{VS}	VS	I _{VS_Sleep}	—	18	30	μA	A
VCC									
1.10	VCC Undervoltage Detection Threshold		VCC	V _{VCC_UV}	4	—	4.5	V	A
1.20	VCC Supply Current	Normal mode (dominant)	VCC	I _{VCC_dom}	20	—	65	mA	A
1.31		Normal mode (recessive)	VCC	I _{VCC_rec}	2	—	6.2	mA	A
1.310		Silent mode	VCC	I _{VCC_sil}	0.2	—	1.8	mA	A
1.32		Normal mode short between CANH and CANL	VCC	I _{VCC_short}	—	—	80	mA	B
1.33		Sleep mode or Standby mode	VCC	I _{VCC_sleep}	—	—	4	μA	A
VIO									
2.10	VIO Undervoltage Detection Threshold		VIO	V _{VIO_UV}	2.4	—	2.8	V	A
2.20	VIO Supply Current	Normal (V _{TXD} = 0V)	VIO	I _{VIO_norm}	—	—	130	μA	A
2.21		Normal mode or Silent mode (recessive)	VIO	I _{VIO_rec}	—	—	4.5	μA	A
2.22		Standby mode or Sleep mode	VIO	I _{VIO_Sleep}	—	—	4.5	μA	A
NSTBY and EN									
3.10	High-Level Input Voltage		NSTBY/EN	V _{NSTBY/EN_H}	0.7 × V _{VIO}	—	V _{VIO} + 0.3	V	A
3.20	Low-Level Input Voltage		NSTBY/EN	V _{NSTBY/EN_L}	−0.3	—	0.3 × V _{VIO}	V	A
3.30	High-Level Input Current	V _{NSTBY} , V _{EN} > 0.7*VIO	NSTBY/EN	I _{NSTBY/EN_H}	1	4	10	μA	A
3.40	Low-Level Input Current	V _{NSTBY} , V _{EN} = 0V	NSTBY/EN	I _{NSTBY/EN_L}	−1	0	+1	μA	B
NERR, RXD									
4.10	High-Level Output Current	V _{NERR/RXD} = V _{VIO} - 0.4V	NERR, RXD	I _{NERR_H, IRXD_H}	−2	—	—	mA	A
4.20	Low-Level Output Current	V _{NERR} = 0.4V	NERR, RXD	I _{NERR_L, IRXD_L}	—	—	2	mA	A
TXD									
5.10	High-Level Input Voltage		TXD	V _{TXD_H}	0.7 × V _{VIO}	—	V _{VIO} + 0.3	V	A
5.20	Low-Level Input Voltage		TXD	V _{TXD_L}	−0.3	—	0.3 × V _{VIO}	V	A
5.30	Pull-Up Resistor		TXD	R _{PU_TXD}	40	60	80	kΩ	A
5.40	Input Capacitance		TXD	C _{TXD}	—	5	10	pF	D
WAKE									
6.10	High-Level Input Current	V _{WAKE} = V _{VS} - 1.9V	WAKE	I _{WAKE_H}	−10	−6	−1	μA	A

Table 7-1. Electrical Characteristics (continued)

No.	Parameters	Test Conditions	Pin	Sym.	Min.	Typ.	Max.	Unit	Type*
6.20	Low-Level Input Current	$V_{WAKE} = V_{VS} - 3.9V$	WAKE	I_{WAKE_L}	1	8	10	μA	A
6.30	Threshold Voltage		WAKE	V_{WAKE_TH}	$V_{VS} - 3.8$	—	$V_{VS} - 2$	V	A
INH									
7.10	High-Level Voltage	Normal mode or Standby mode, $I_{INH} = -180 \mu A$	INH	V_{INH_H}	$V_{VS} - 0.8$	—	V_{VS}	V	A
7.20	Off Mode Leakage Current	Off mode leakage current, INH pin grounded	INH	I_{INH_OFF}	-2	—	2	μA	A
CANH, CANL (see Figure 8-2 for the definition of R_L and the test circuit)									
8.10	Single-Ended Dominant Output Voltage	$R_L = 50\Omega$ to 65Ω	CANH	V_{CANH}	2.75	3.5	4.5	V	A
8.11			CANL	V_{CANL}	0.5	1.5	2.25	V	A
8.30	Transmitter Voltage Symmetry	$V_{Sym} = (V_{CANH} + V_{CANL})/V_{CC}$, $R_L = 60\Omega$, $C_t = 4.7 \text{ nF}$, $f_{TXD} = 1 \text{ MHz}$	—	V_{SYM}	0.9	—	1.1	V	D
8.40	Dominant Differential Output Voltage	Normal mode, $V_{TXD} = 0V$, $V_{VCC} = 4.7V$ to $5.5V$, $t < t_{to(dom)}$ $R_L = 50\Omega$ to 65Ω	—	V_{Diff}	1.5	—	3	V	B
8.41		Normal mode, $V_{TXD} = 0V$, $V_{VCC} = 4.7V$ to $5.5V$, $t < t_{to(dom)}$ $R_L = 45\Omega$ to 70Ω	—	V_{Diff}	1.4	—	3.2	V	B
8.42		Normal mode, $V_{TXD} = 0V$, $V_{VCC} = 4.7V$ to $5.5V$, $t < t_{to(dom)}$ $R_L = 2240\Omega$	—	V_{Diff}	1.5	—	5	V	D
8.50	Recessive Output Voltage	Single-Ended output voltage on CANH/CANL, Normal mode/Silent mode, $V_{TXD} = V_{VIO}$, no load	CANH, CANL	V_{CANH}, V_{CANL}	2	$0.5 \times V_{VCC}$	3	V	A
8.51		Single-Ended output voltage on CANH/CANL, Standby mode, $V_{TXD} = V_{VIO}$, no load	CANH, CANL	V_{CANH}, V_{CANL}	-0.1	—	0.1	V	A
8.53		Differential output voltage (bus biasing active), no load	CANH, CANL	V_{Diff}	-50	—	50	mV	A
8.54		Differential output voltage (bus biasing inactive), no load	CANH, CANL	V_{Diff}	-200	—	200	mV	A
8.60	Differential Receiver Threshold Voltage	Normal/Silent mode; $V_{CANL} = V_{CANH} = -12V$ to $+12V$	—	$V_{Diff_rx_th}$	0.5	0.7	0.9	V	A
8.61		Standby/Sleep mode; $V_{CANL} = V_{CANH} = -12V$ to $+12V$	—	$V_{Diff_rx_th}$	0.4	0.7	1.15	V	A
8.70	Differential Receiver Hysteresis Voltage	Normal/Silent mode; $V_{CANL} = V_{CANH} = -12V$ to $+12V$	—	V_{hys_rx}	50	120	200	mV	B
8.80	Input Leakage Current	$V_{VS} = V_{VCC} = V_{VIO} = 0V$, $V_{CANH} = V_{CANL} = 5V$	—	$I_{leak_in} (I_{CANH}, I_{CANL})$	-5	—	+5	μA	A
		$V_{VS} = V_{VCC} = V_{VIO}$ shorted to ground through $47 \text{ k}\Omega$, $V_{CANH} = V_{CANL} = 5V$	—	$I_{leak_in} (I_{CANH}, I_{CANL})$	-5	—	+5	μA	D
8.90	Maximum Driver Output Current	Normal mode, CAN dominant, $V_{TXD} = 0$, $t < t_{to(dom)}$, $V_{VCC} = 5V$, $V_{CANH} = -5V$ (short circuit)	—	I_{CANH_max}	-100	—	-35	mA	A
8.91		Normal mode, CAN dominant; $V_{TXD} = 0$, $t < t_{dom}$, $V_{VCC} = 5V$, $V_{CANL} = 18V$ (short circuit)	—	I_{CANL_max}	35	—	100	mA	A
8.92		Normal mode, CAN dominant; $V_{TXD} = 0$, $t < t_{dom}$, $V_{VCC} = 5V$, $V_{CANL} = 27V$ (short circuit)	—	I_{CANL_max}	35	—	115	mA	D
8.100	Single-Ended Input Resistance	$V_{CANH} = V_{CANL} = 4V$	CANH, CANL	R_{CANH}, R_{CANL}	9	15	28	k Ω	A
		$-2V \leq V_{CANH} \leq 7V$, $-2V \leq V_{CANL} \leq 7V$	CANH, CANL	R_{CANH}, R_{CANL}	9	15	28	k Ω	D

Table 7-1. Electrical Characteristics (continued)

No.	Parameters	Test Conditions	Pin	Sym.	Min.	Typ.	Max.	Unit	Type*
8.110	Matching of Internal Resistance Between CANH and CANL	$V_{CANH} = V_{CANL} = 4V$, $mR = 2 \times (R_{CANH} - R_{CANL}) / (R_{CANH} + R_{CANL})$	—	mR	-1	—	1	%	A
		$-2V \leq V_{CANH} \leq 7V$, $-2V \leq V_{CANL} \leq 7V$ $mR = 2 \times (R_{CANH} - R_{CANL}) / (R_{CANH} + R_{CANL})$	—	mR	-1	—	1	%	D
8.120	Differential Internal Resistance	$V_{CANH} = V_{CANL} = 4V$	—	R_{Diff}	18	30	56	kΩ	A
		$-2V \leq V_{CANH} \leq 7V$, $-2V \leq V_{CANL} \leq 7V$	—	R_{Diff}	18	30	56	kΩ	D
8.130	Common-Mode Input Capacitance	f=500kHz, CANH and CANL referring to ground	—	$C_{l(cm)}$	—	—	20	pF	D
8.140	Differential Input Capacitance	f=500kHz, between CANH and CANL	—	C_{Diff}	—	—	10	pF	D
8.141	Differential Bus Voltage Range for Recessive State Detection	Bus biasing active /inactive $-12.0V \leq V_{CANL} \leq +12.0V$ $-12.0V \leq V_{CANH} \leq +12.0V$	—	$V_{Diff_rec_a}$ $V_{Diff_rec_l}$	-3 -3	— —	+0.5 +0.4	V	D
8.142	Differential Bus Voltage Range for Dominant State Detection	Bus biasing active /inactive $-12.0V \leq V_{CANL} \leq +12.0V$ $-12.0V \leq V_{CANH} \leq +12.0V$	—	$V_{DIFF_dom_a}$ $V_{DIFF_dom_l}$	0.9 1.15	— —	8 8	V	D
Transceiver Timing, Pins WAKE, INH, CANH, CANL, TXD and RXD. See Figure 7-1, Figure 7-2 and Figure 8-2 for the definition of the timing parameters and the test circuit.									
9.10	Delay Time from TXD to Bus Dominant	$R_L = 60\Omega$, $C_2 = 100\text{ pF}$	CANH, CANL, TXD	t_{TXDBUS_dom}	—	65	—	ns	C
9.20	Delay Time from TXD to Bus Recessive	$R_L = 60\Omega$, $C_2 = 100\text{ pF}$	CANH, CANL, TXD	t_{TXDBUS_rec}	—	90	—	ns	C
9.30	Delay Time from bus Dominant to RXD	$R_L = 60\Omega$, $C_2 = 100\text{ pF}$	CANH, CANL, RXD	t_{BUSRXD_dom}	—	60	—	ns	C
9.40	Delay Time from Bus Recessive to RXD	$R_L = 60\Omega$, $C_2 = 100\text{ pF}$	CANH, CANL, RXD	t_{BUSRXD_rec}	—	65	—	ns	C
9.50	Propagation Delay from TXD to RXD	$R_L = 60\Omega$, $C_2 = 100\text{ pF}$, $C_{RXD} = 22\text{ pF}$, $R_{RXD} = 510\Omega$	TXD, RXD	t_{Loop}	100	—	255	ns	A
9.51		$R_L = 150\Omega$, $C_2 = 100\text{ pF}$, $C_{RXD} = 22\text{ pF}$, $R_{RXD} = 510\Omega$, $f_{TXD} = 250\text{ KHz}$	TXD, RXD	t_{Loop}	—	—	300	ns	C
9.60	Recessive Bit Time on Pin RXD	$t_{B_TXD} = 500\text{ ns}$, $R_L = 60\Omega$, $C_2 = 100\text{ pF}$, $C_{RXD} = 22\text{ pF}$, $R_{RXD} = 510\Omega$	RXD	$t_{Bit(RXD)}$	400	—	550	ns	C
9.61		$t_{B_TXD} = 200\text{ ns}$, $R_L = 60\Omega$, $C_2 = 100\text{ pF}$, $C_{RXD} = 22\text{ pF}$, $R_{RXD} = 510\Omega$	RXD	$t_{Bit(RXD)}$	120	—	220	ns	A
9.70	Receiver Timing Symmetry	$\Delta t_{Rec} = t_{Bit(RXD)} - t_{Bit(Bus)}$, $t_{B_TXD} = 500\text{ ns}$ (see no. 9.100 for $t_{Bit(Bus)}$) $R_L = 60\Omega$, $C_2 = 100\text{ pF}$, $C_{RXD} = 22\text{ pF}$, $R_{RXD} = 510\Omega$	—	Δt_{Rec}	-65	—	+40	ns	C
9.71		$\Delta t_{Rec} = t_{Bit(RXD)} - t_{Bit(Bus)}$, $t_{B_TXD} = 200\text{ ns}$ $R_L = 60\Omega$, $C_2 = 100\text{ pF}$, $C_{RXD} = 22\text{ pF}$, $R_{RXD} = 510\Omega$	—	Δt_{Rec}	-45	—	+15	ns	B
9.80	TXD Dominant Time-Out Time	$V_{TXD} = 0V$, Normal mode	TXD	$t_{to(dom)}$	2.7	—	3.3	ms	B
9.90	Bus Dominant Time-Out Time	$V_{CANH-CANL} = 0.9V$	—	t_{BUS_dom}	2.7	—	3.3	ms	B
9.100	Transmitted Recessive Bit Width on the Bus	$t_{B_TXD} = 500\text{ ns}$ $R_L = 60\Omega$, $C_2 = 100\text{ pF}$, $C_{RXD} = 22\text{ pF}$, $R_{RXD} = 510\Omega$	—	$t_{Bit(Bus)}$	435	—	530	ns	C
9.110		$t_{B_TXD} = 200\text{ ns}$ $R_L = 60\Omega$, $C_2 = 100\text{ pF}$, $C_{RXD} = 22\text{ pF}$, $R_{RXD} = 510\Omega$	—	$t_{Bit(Bus)}$	155	—	210	ns	A

Table 7-1. Electrical Characteristics (continued)

No.	Parameters	Test Conditions	Pin	Sym.	Min.	Typ.	Max.	Unit	Type*
9.120	CAN Activity Filter Time for Standard Remote Wake-Up Pattern (WUP)	First pulse (after first recessive) and second pulse for wake-up on pins CANH and CANL, Sleep mode	CANH, CANL	t_{filter}	0.5	—	1.8	μs	A
9.170	Go-to-Sleep Hold Time	From issuing the Go-to-Sleep command to enter Sleep mode	—	t_{hold}	20	—	50	μs	B
9.180	Undervoltage Detection Time		VCC, VIO	$t_{\text{VSUP_UV_set}}$	100	—	350	ms	B
9.190	Undervoltage Recovery Time		VCC, VIO	$t_{\text{VSUP_UV_clear}}$	1	—	5	ms	B
9.200	Start-Up Time after Power-On	From V_{VS} rises above the power-on detection threshold, $V_{\text{VS_PWON}}$ until pin INH high	VS	t_{startup}	—	0.5	1	ms	A
9.220	Debouncing Time for Recessive Clamping State Detection	$V_{\text{CANH}} + V_{\text{CANL}} > 900 \text{ mV}$, RXD = HIGH	RXD	$t_{\text{RXD_rec_clmp}}$	60	90	175	ns	D
9.230	Local Wake-Up Filter Time	In response to a falling or rising edge on pin WAKE; Standby or Sleep mode	WAKE	$t_{\text{local_wu}}$	5	—	50	μs	A
9.240	Transmitter Resume Time	From TXD, it goes high to TX and it operates after the TXD dominant timeout event is detected	—	$t_{\text{TX_resume_TXDOUT}}$	—	—	4	μs	D
9.250	Bus Wake-Up Time-Out Time	Between the first and second dominant pulses, CAN TRX Standby mode	—	t_{wake}	0.9	—	1.2	ms	B
9.260	Delay Time for Standby to Normal Mode Transition	Rising edge at pin NSTBY, EN = HIGH	—	$t_{\text{del(stby-norm)}}$	—	—	47	μs	D
9.270	Delay Time for Normal Mode to Standby Mode Transition	Falling edge at pin NSTBY, EN = LOW	—	$t_{\text{del(norm-stby)}}$	—	—	5	μs	D
9.280	Delay Time for Normal Mode to Silent Mode Transition	Falling edge at pin EN, NSTBY = HIGH	—	$t_{\text{del(norm-silent)}}$	—	—	10	μs	D
9.290	Delay Time for Silent Mode to Normal Mode Transition	Rising edge at pin EN, NSTBY = HIGH	—	$t_{\text{del(silent-norm)}}$	—	—	10	μs	D
9.300	Delay Time for Silent Mode to Standby Mode Transition	Falling edge at pin EN, NSTBY = LOW	—	$t_{\text{del(silent-stby)}}$	—	—	5	μs	D
9.310	Delay Time for Standby Mode to Silent Mode Transition	Rising edge at pin NSTBY, EN = LOW	—	$t_{\text{del(stby-silent)}}$	—	—	47	μs	D
9.320	Delay Time for Sleep Mode to Standby Mode Transition	Wake event detected	—	$t_{\text{del(sleep-stby)}}$	—	—	5	μs	D

* Type means: A = 100% tested, B = 100% correlation tested, C = Characterized on samples, D = Design parameter.

Figure 7-1. CAN Transceiver Timing Diagram 1

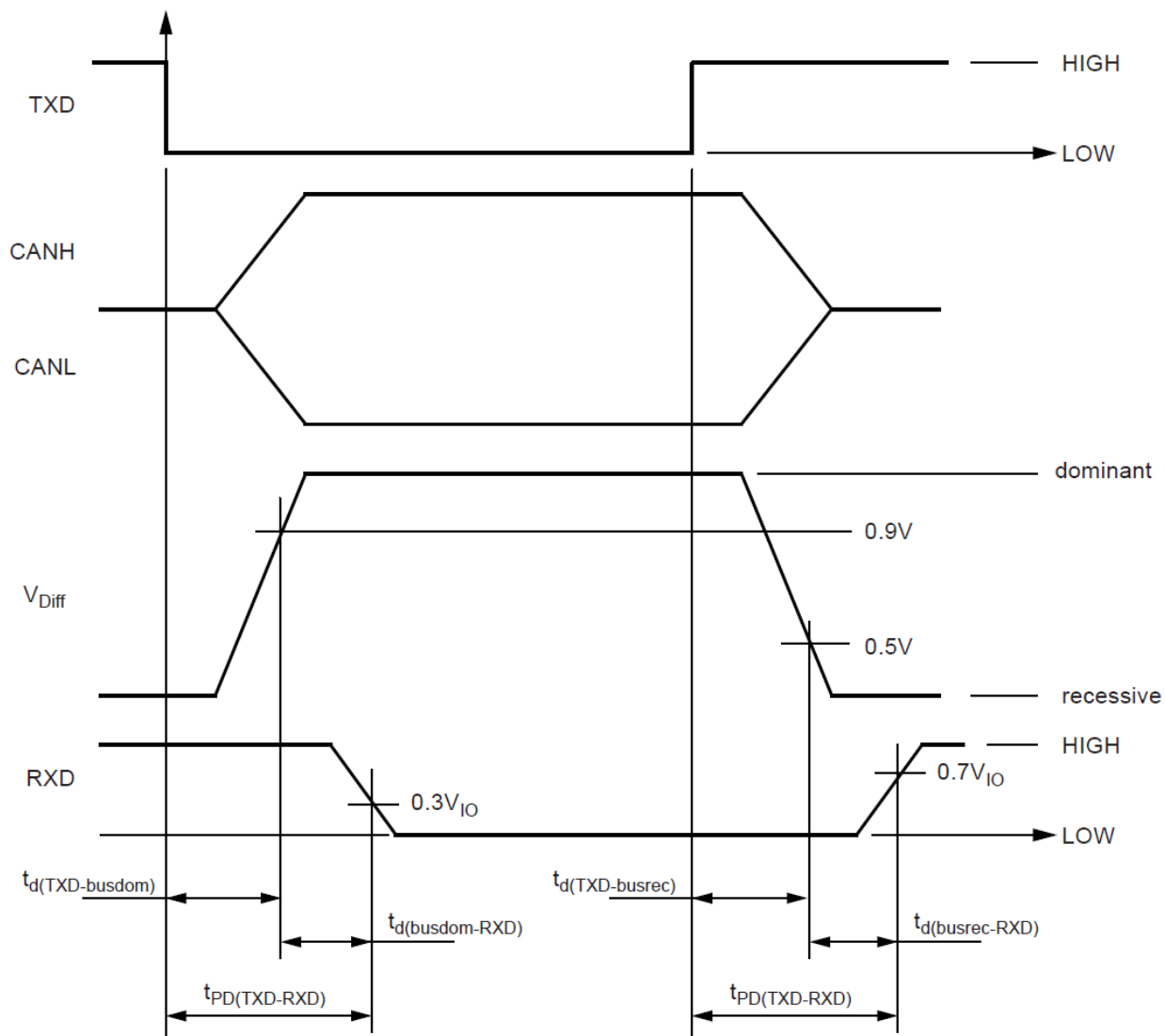
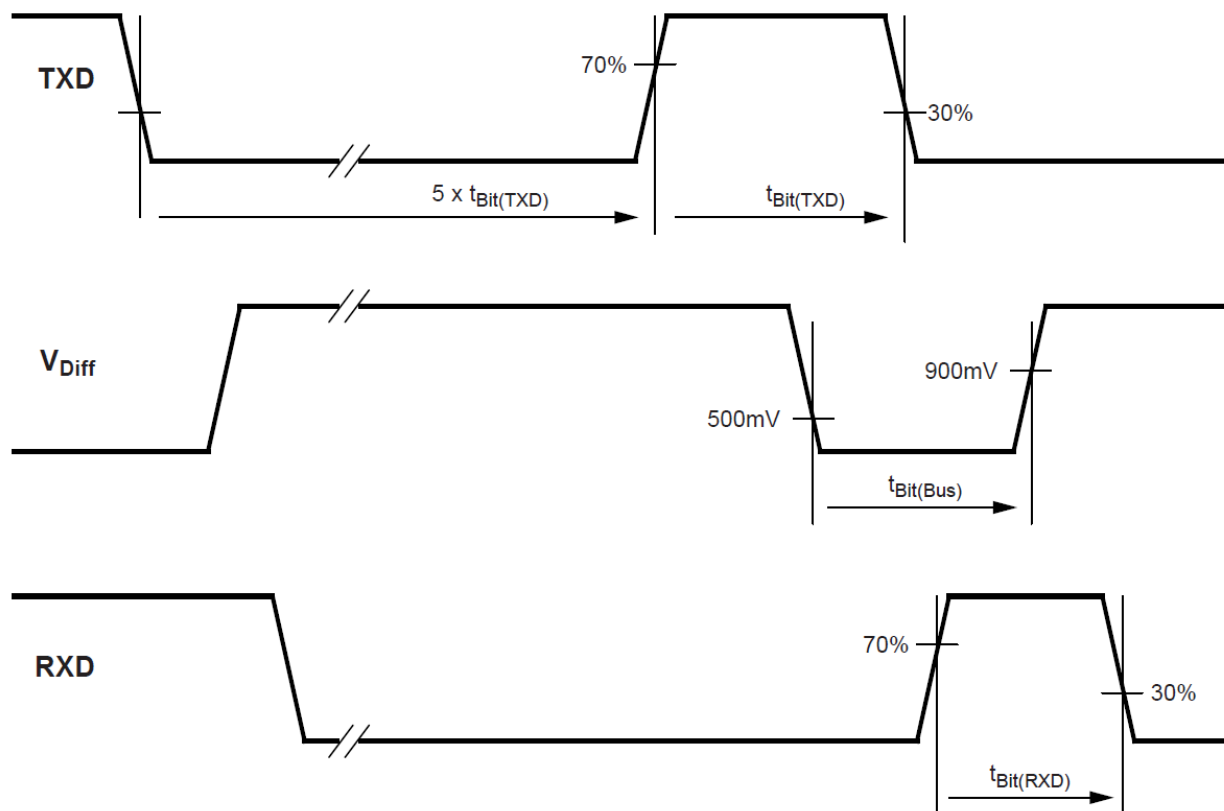


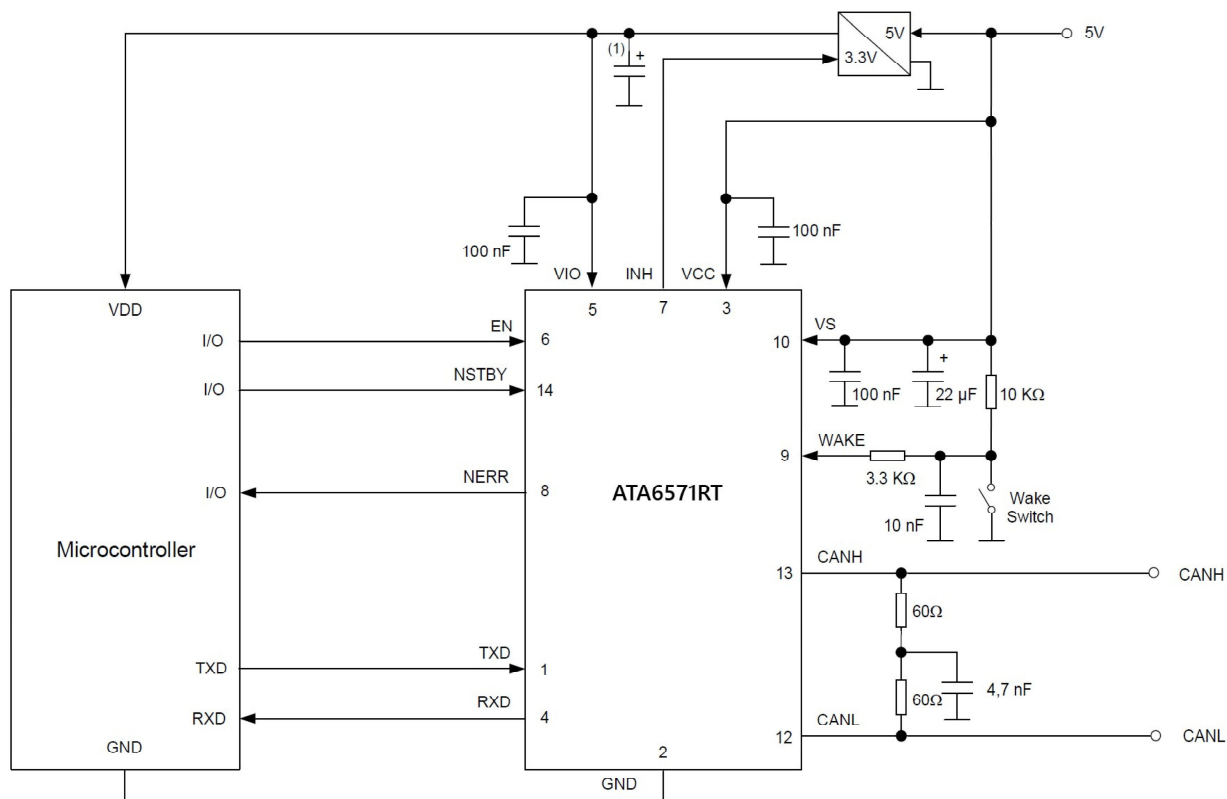
Figure 7-2. CAN Transceiver Timing Diagram 2



8. Application Circuits

The following figure shows the application circuit.

Figure 8-1. Typical Application Circuit

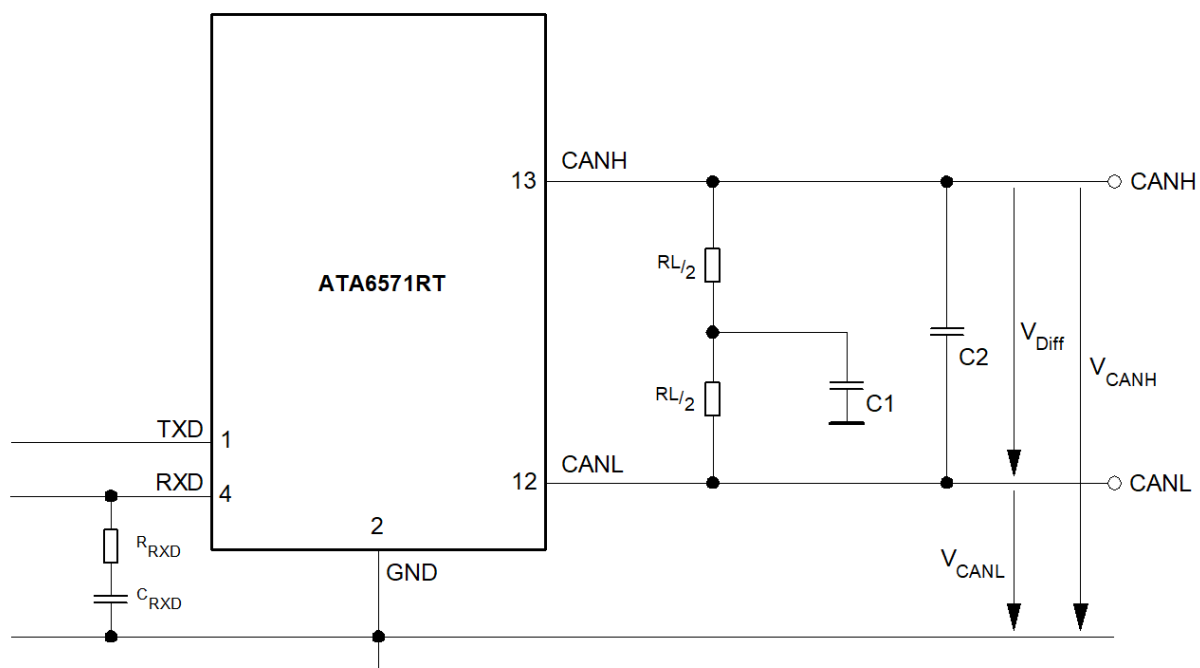


Note:

1. The value of this capacitor depends on the used external voltage regulator.

The following figure shows the test circuit.

Figure 8-2. Test Circuit



9. Package Information

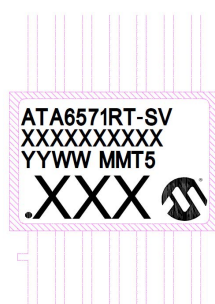
This section discusses the package information.

9.1. Package Marking Information

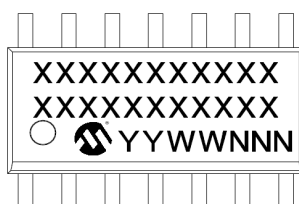
The following figure shows the package marking information.

Figure 9-1. Package Marking

14-Lead CDFP



14-Lead 3.90 mm SOIC

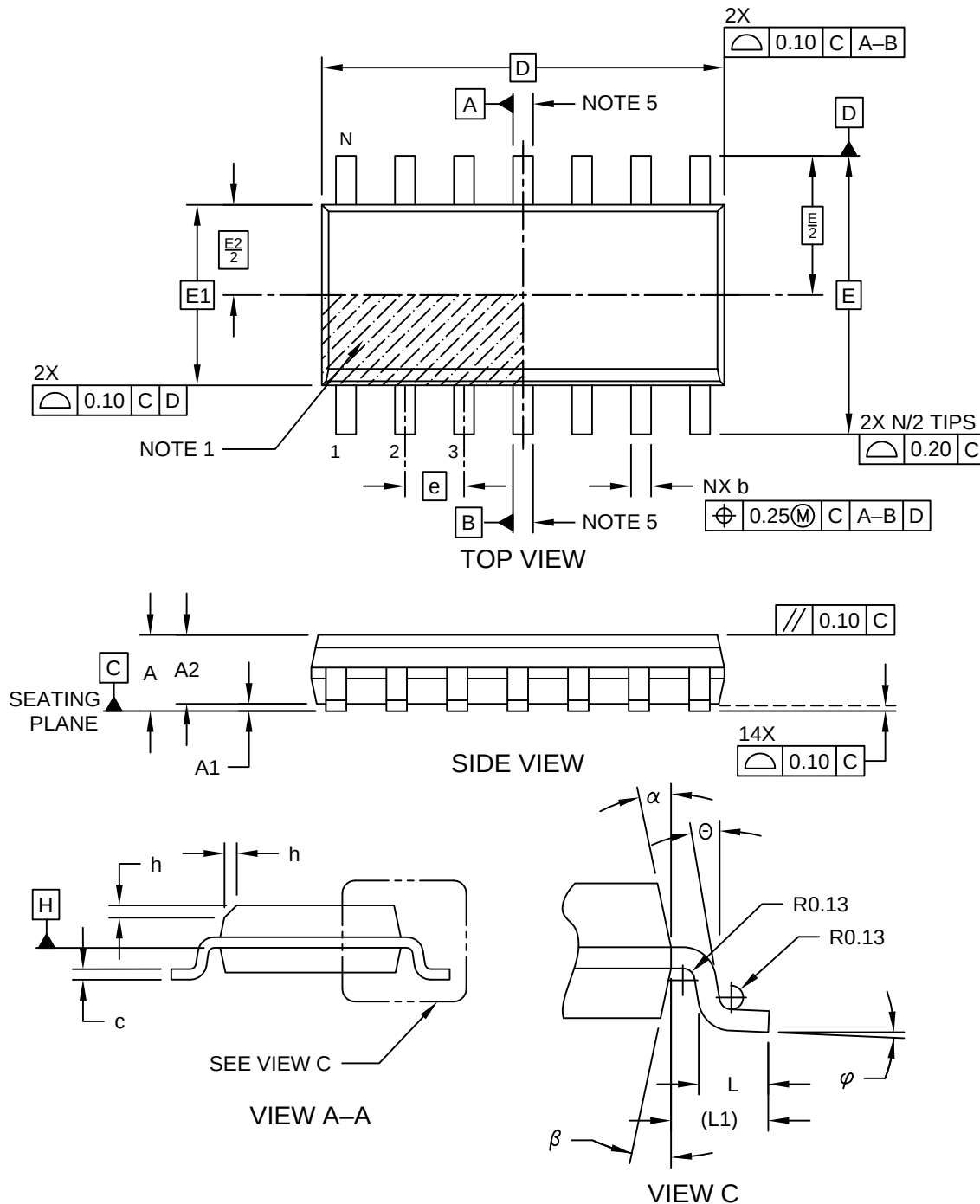


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.
Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.		

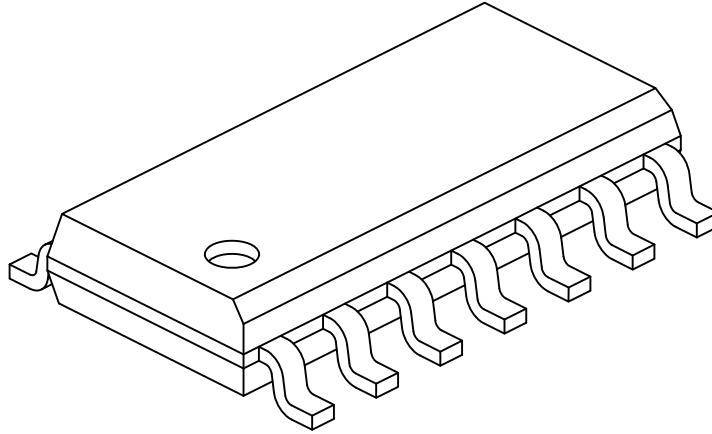
9.2. Package Drawings

The following figures show the package drawings information.

Figure 9-2. 14-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]



Note: For the most current package drawings, see the Microchip Packaging Specification located at www.microchip.com/packaging.

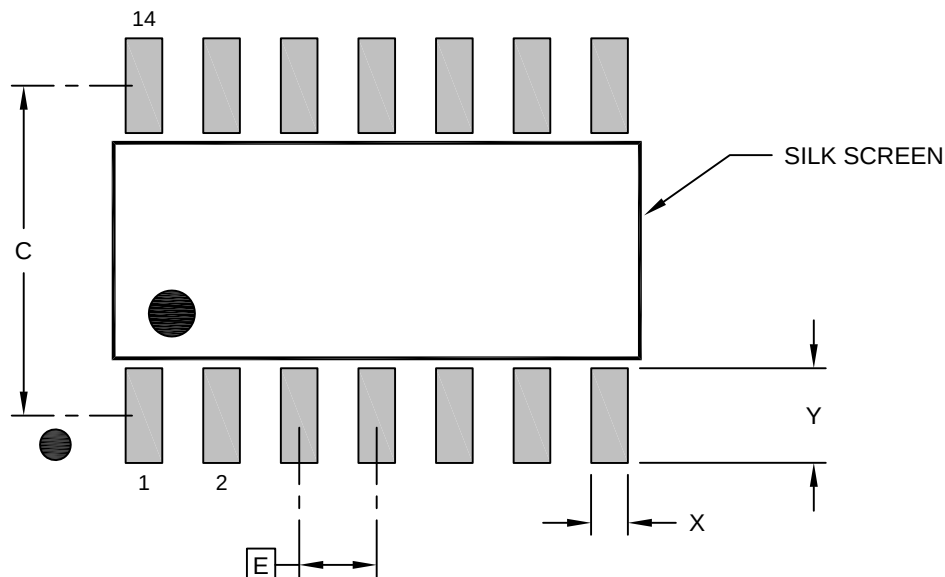
Figure 9-3. 14-Lead Plastic Small Outline (SL)—Narrow, 3.90 mm Body [SOIC]

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	14		
Pitch	e	1.27 BSC		
Overall Height	A	-	-	1.75
Molded Package Thickness	A2	1.25	-	-
Standoff §	A1	0.10	-	0.25
Overall Width	E	6.00 BSC		
Molded Package Width	E1	3.90 BSC		
Overall Length	D	8.65 BSC		
Chamfer (Optional)	h	0.25	-	0.50
Foot Length	L	0.40	-	1.27
Footprint	L1	1.04 REF		
Lead Angle	θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.10	-	0.25
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.
- Datums A & B to be determined at Datum H.

Figure 9-4. 14-Lead Plastic Small Outline (SL)—Narrow, 3.90 mm Body [SOIC]



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	C		5.40	
Contact Pad Width (X14)	X			0.60
Contact Pad Length (X14)	Y			1.55

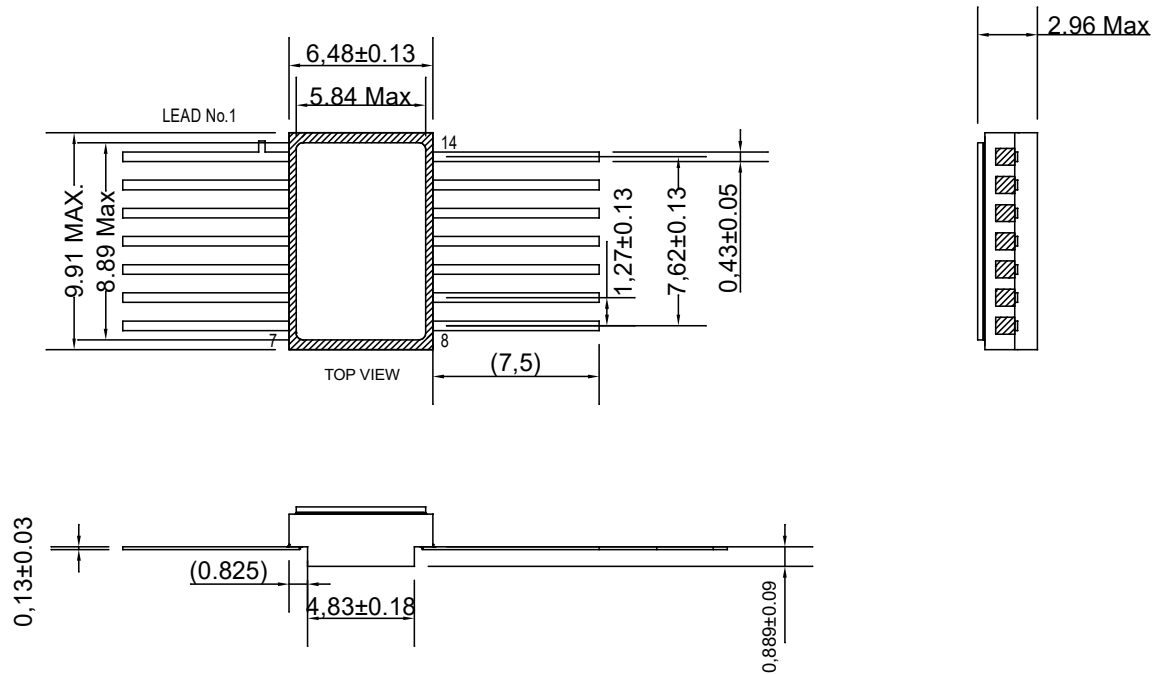
Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Note: For the most current package drawings, see the Microchip Packaging Specification located at www.microchip.com/packaging.

Figure 9-5. 14 -Lead Ceramic Dual Flat Pack (XGB) 6.48 × 9.91 mm with Flat Leads [CDFP]



Note: For the most current package drawings, see the Microchip Packaging Specification located at www.microchip.com/packaging.

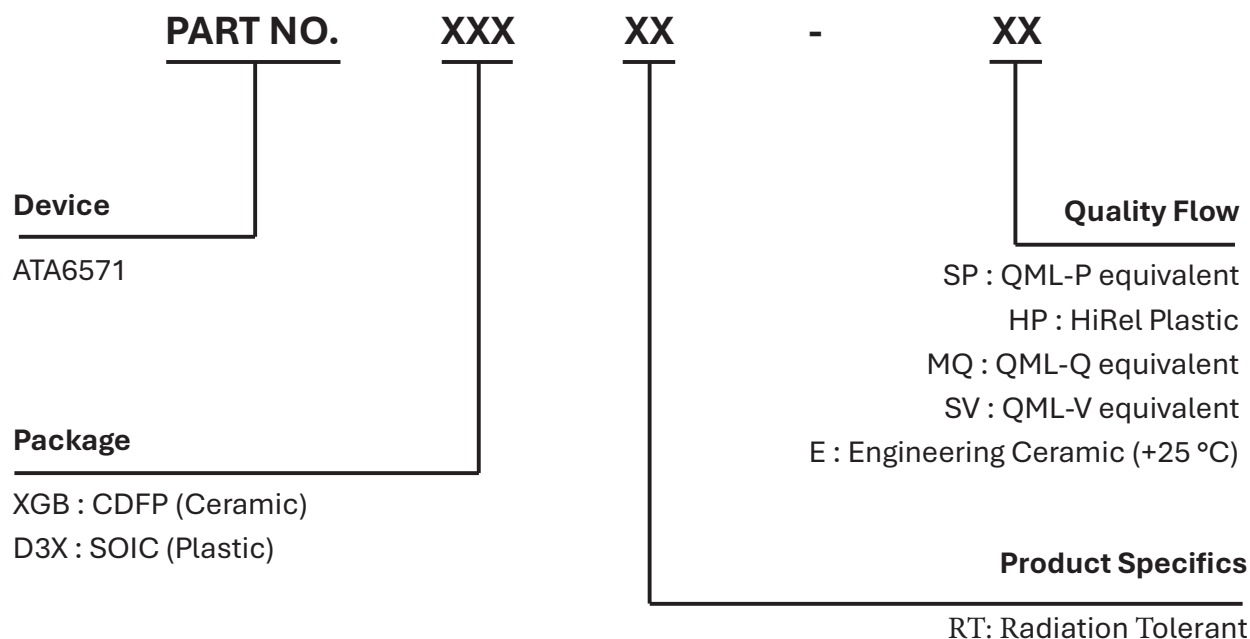
10. Ordering Information

This section discusses the ordering information of ATA6571RT.

Product Identification System

The following figure shows the product identification system of ATA6571RT.

Figure 10-1. Product Identification System



Valid Combinations

For more information on ATA6571RT device availability and ordering, contact your authorized Microchip Technology sales representative.

The following table lists the ATA6571RT ordering information.

Table 10-1. ATA6571RT Ordering Information

Ordering Code	Package	Operating Temperature	Quality Flow
ATA6571XGBRT-E	CDFP14	25 °C	Engineering Samples
ATA6571XGBRT-MQ		-55 °C to +125 °C	QML-Q Equivalent
ATA6571XGBRT-SV			QML-V Equivalent
ATA6571D3XRT-HP	SOIC14		High-Reliability Plastic
ATA6571D3XRT-SP			QML-P Equivalent

11. Revision History

The revision history describes the changes that were implemented in the document. The changes are listed by revision, starting with the most current publication.

Table 11-1. Revision History

Revision	Date	Description
B	06/2026	The following is the list of changes made in this revision of the document. • Updated the Features section. • Updated Table 5-1 in the Absolute Maximum Ratings section. • Updated Table 6-1 and Table 6-2 in the Thermal Characteristics section. • Updated the Electrical Characteristics section. • Updated Figure 8-2.
A	06/2025	Initial Revision

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